COMPONENT PACKAGING APPARATUS, SYSTEMS, AND METHODS

Abstract of the Disclosure

A method and apparatus to imprint or emboss dielectric substrates for highdensity electronic circuitry using tool foils having a special release coating.

"Express Mail" mailing label number: <u>EV370238775US</u> This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is

addressed to the Commissioner for Patents, Mail Stop Patent Application, P.O. Box 1450, Alexandria, VA 22313-1450.

5